Celanese
The chemistry inside innovation™

HOSTAFORM® S 9244 XAP®2

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POM copolymer, modified Injection molding type, elastomer-containing; with higher impact strength and slightly lower hardness, rigidity and chemical resistance than unmodified acetal copolymer. Reduced emission grade, Emission according to VDA 275 < 5 mg/kg good weld strength. Preliminary Datasheet

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	1.4	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	1.7	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.6	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	1450	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	33	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	7	%	ISO 527-1/-2
Nominal strain at break	>50	%	ISO 527-1/-2
Flexural modulus	1450	MPa	ISO 178
Tensile creep modulus, 1h	1200	MPa	ISO 899-1
Tensile creep modulus, 1000h	650	MPa	ISO 899-1
Charpy impact strength, 23°C	N	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	200[P]	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	18	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	12	kJ/m^2	ISO 179/1eA
Poisson's ratio	0.43[C]		

[P]: Partial Break

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	68	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	130	E-6/K	ISO 11359-1/-2

Electrical properties

Relative permittivity, 100Hz	3.6		IEC 62631-2-1
Relative permittivity, 1MHz	3.6		IEC 62631-2-1
Dissipation factor, 100Hz	40	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	60	E-4	IEC 62631-2-1
Volume resistivity	1E11	Ohm.m	IEC 62631-3-1
Surface resistivity	1E13	Ohm	IEC 62631-3-2
Comparative tracking index	600		IEC 60112

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Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	1.2	%	Sim. to ISO 62
Density	1260	kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	195	°C
Min. melt temperature	190	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	70	°C
Min. mould temperature	60	°C
Max. mould temperature	80	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low emissions, Improved weld line

Additional information

Injection molding

Processing

Above pressures, including back pressure, are given as specific or plastic pressures. The back pressure on Hostaform® and Celcon® POM materials should be as low as possible, just enough to remove air from the pellets during feeding.

Processing Notes

Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose

Storage

The product can then be stored in standard conditions until processed.

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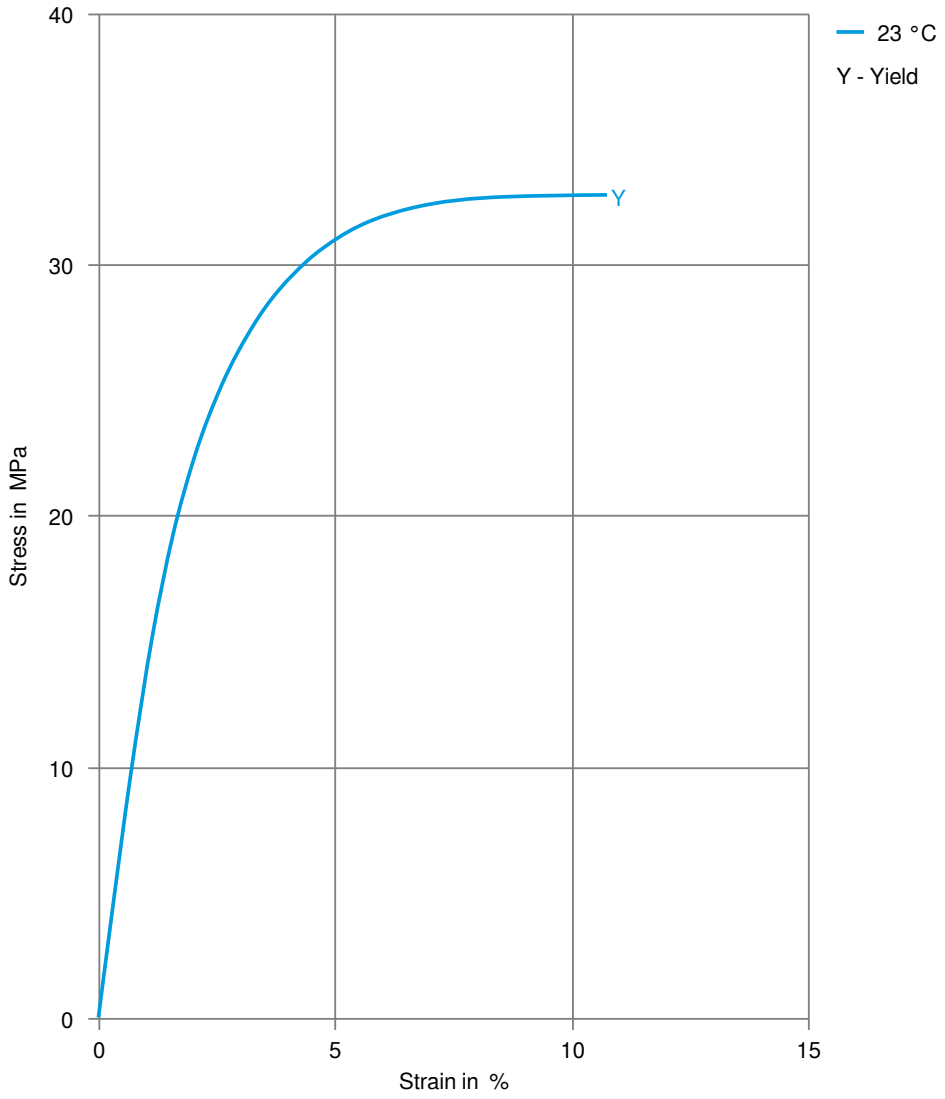
Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Mercedes-Benz	DBL5404	BQF
Renault	UB15, No Spec, Special Part Approval, See Your CE Account Manager.	

Stress-strain



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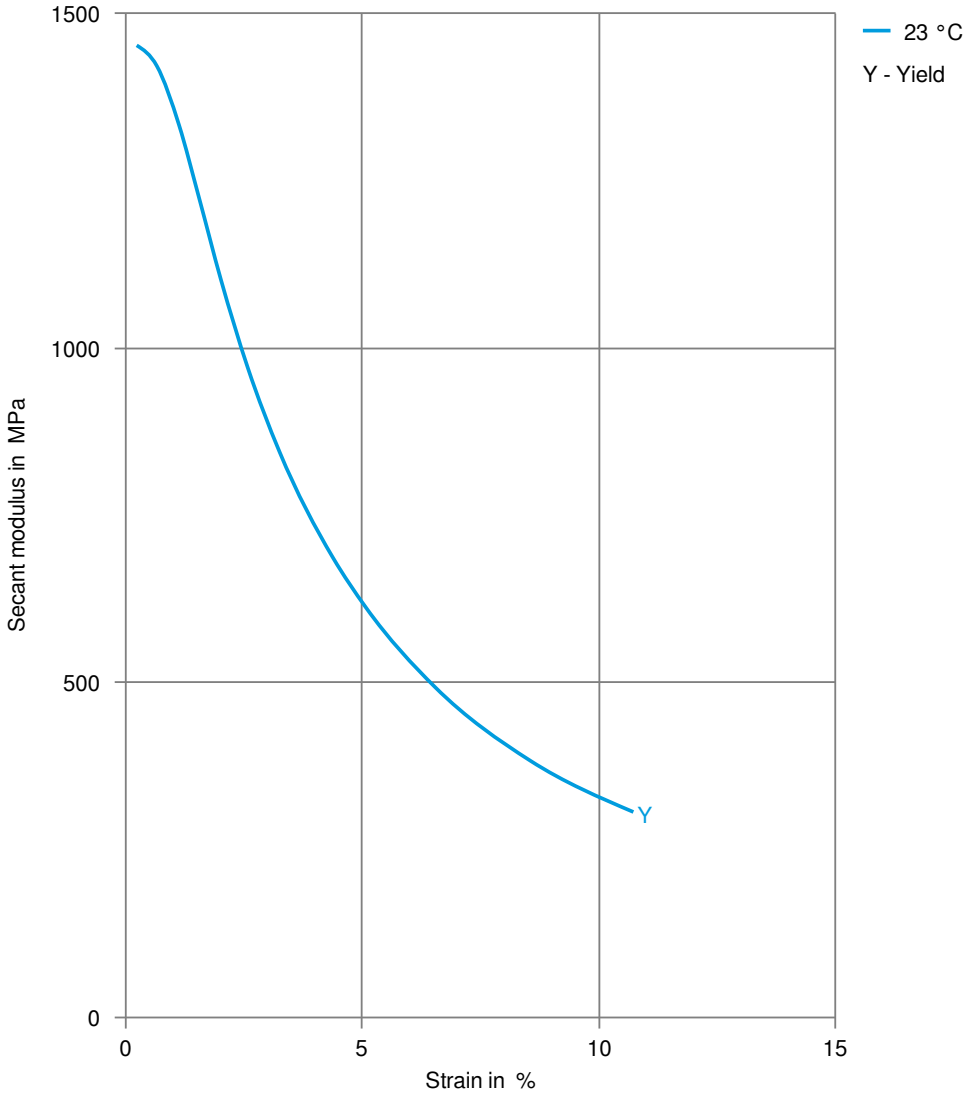
Secant modulus-strain



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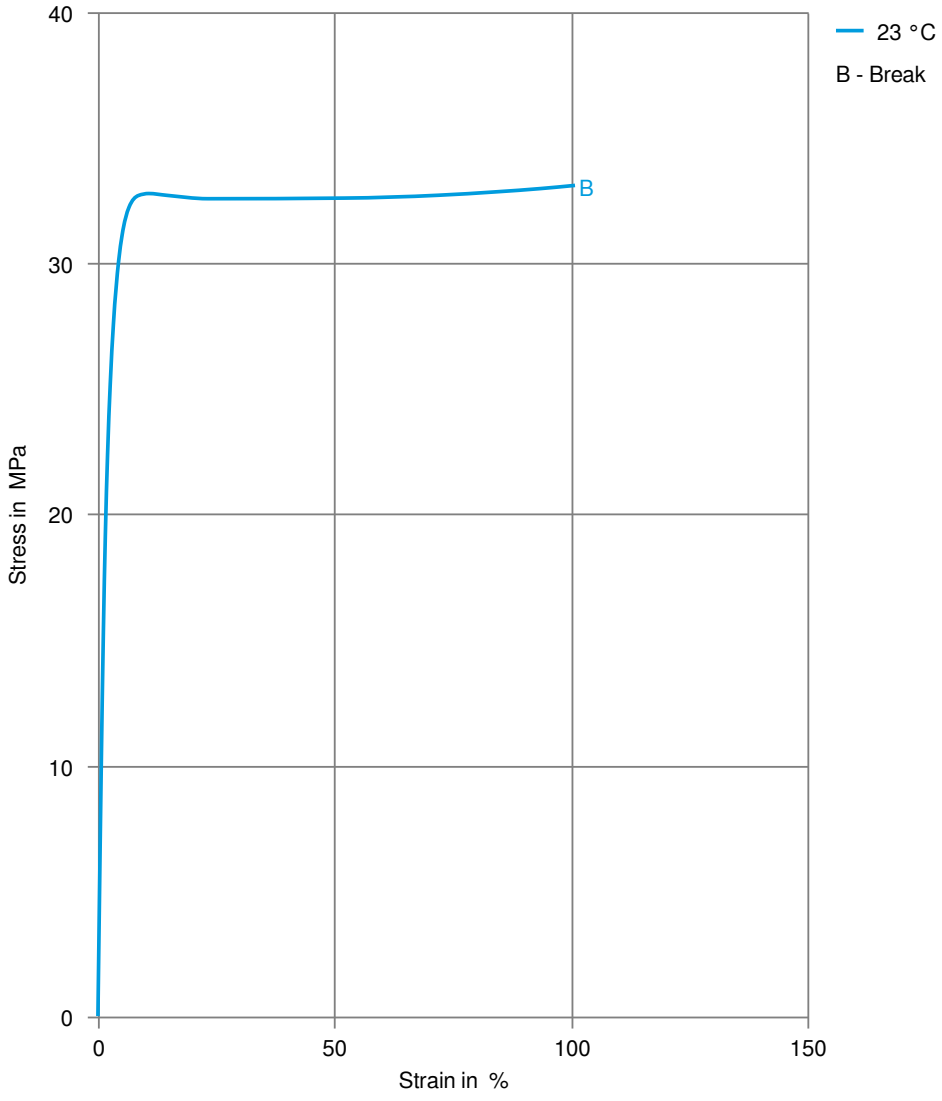
Stress-strain, 50mm/min



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Secant modulus-strain, 50mm/min